

U.S. Express Mail Label No.: EH920330411US

PATENT (U.S.A.)  
ATTORNEY'S DOCKET NO.: UMC-96-279

DECLARATION  
and POWER OF ATTORNEY

X ORIGINAL  
CONTINUATION  
DIVISIONAL

As the below named inventors, we declare that the information given herein is true, that we believe that we are the original inventors of the invention entitled:

High Density Plasma Chemical Vapor Deposition Process

Which is described and claimed in:

- x the attached specification or  
the specification in application Serial No. filed  
as amended on \_\_\_\_\_

(for declaration not accompanying application) (if applicable)

and for which a patent is sought, and that our residences, post office addresses and citizenship are as stated below next to our names.

We acknowledge our duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations § 1.56(a).

We hereby state that we have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

We hereby claim foreign priority benefits under Title 35, United States, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

COUNTRY	APPLICATION NUMBER	DATE OF FILING Month Day Year	PRIORITY CLAIMED UNDER 35 U.S.C. 119
			<input type="checkbox"/> YES
			<input type="checkbox"/> YES

We hereby claim priority benefits under Title 35, United States, § 119(e) of any provisional application(s) listed below:

COUNTRY	APPLICATION NUMBER	DATE OF FILING Month Day Year	PRIORITY CLAIMED UNDER 35 U.S.C. 119
	60/041,790	April 2, 1997	<input checked="" type="checkbox"/> YES
			<input type="checkbox"/> YES

We hereby claim the benefit under Title 335, United States Code § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code § 112, we acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application.

(Application Serial No.) (Filing Date) (Status)

POWER OF ATTORNEY: As a named Inventor, I hereby appoint the following attorney(s) and/or Agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith:

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**DECLARATION and POWER OF ATTORNEY**  
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We further declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

SIGNATURE OF INVENTOR 1 <i>Liu, Chih-Chien</i>		SIGNATURE OF INVENTOR 2 <i>Ta-Shan Tseng</i>	
DATE	6/24/97	DATE	6/24/97
SIGNATURE OF INVENTOR 3 <i>W.B. Shieh</i>		SIGNATURE OF INVENTOR 4 <i>J.Y. Wu</i>	
DATE	7/1/1997	DATE	6/25/97
SIGNATURE OF INVENTOR 5 <i>Water Lur</i>		SIGNATURE OF INVENTOR 6 <i>Shih-Wei Sun</i>	
DATE	Jun. 24, 1997	DATE	6/25/97